

MH180 Hall-effect sensor is a temperature stable, stress-resistant sensor. Superior high-temperature performance is made possible through a dynamic offset cancellation that utilizes chopper-stabilization. This method reduces the offset voltage normally caused by device over molding, temperature dependencies, and thermal stress.

MH180 includes the following on a single silicon chip: voltage regulator, Hall voltage generator, small-signal amplifier, chopper stabilization, Schmitt trigger, Advanced DMOS wafer fabrication processing is used to take advantage of low-voltage requirements, component matching, very low input-offset errors, and small component geometries.

This device requires the presence of both south and north polarity magnetic fields for operation. In the presence of a south polarity field of sufficient strength, the device output sensor on, and only switches off when a north polarity field of sufficient strength is present.

MH180 is rated for operation between the ambient temperatures -40°C and 85°C for the E temperature range, and -40°C to 125°C for the K temperature range. The two package styles available provide magnetically optimized solutions for most applications. Package SO is an SOT-23, a miniature low-profile surface-mount package, while package UA is a three-lead ultra mini SIP for through-hole mounting.

Packages is Halogen Free standard and which have been verified by third party lab.

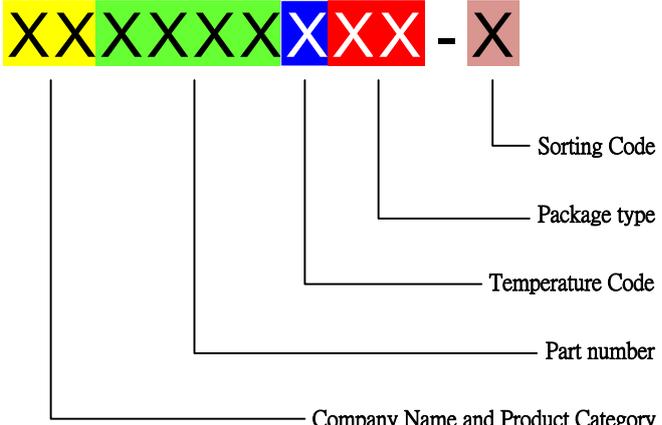
Features and Benefits

- DMOS Hall IC Technology.
- Reverse bias protection on power supply pin.
- Chopper stabilized amplifier stage.
- Optimized for BLDC motor applications.
- Reliable and low shifting on high Temp condition.
- Good ESD Protection.
- 100% tested at 125°C for K.
- Custom sensitivity / Temperature selection are available.

Applications

- High temperature Fan motor
- 3 phase BLDC motor application
- Speed sensing
- Position sensing
- Current sensing
- Revolution counting
- Solid-State Switch
- Linear Position Detection
- Angular Position Detection
- Proximity Detection
- High ESD Capability

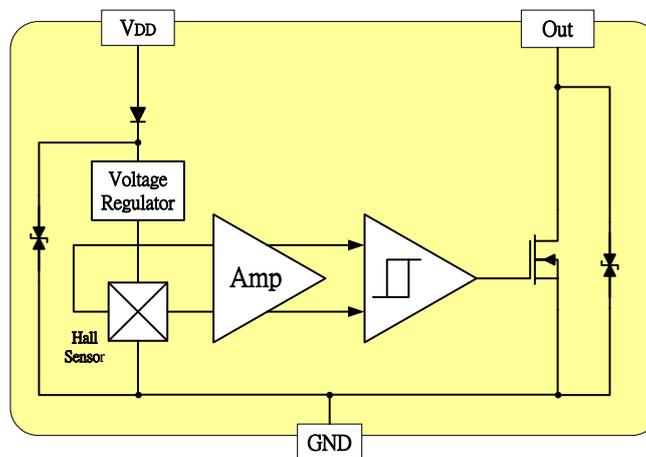
Ordering Information

	<p>Company Name and Product Category MH:MST Hall Effect/MP:MST Power IC</p> <p>Part number 181,182,183,184,185,248,249,276,477,381,381F,381R,382..... If part # is just 3 digits, the fourth digit will be omitted.</p> <p>Temperature range E: 85 °C, I: 105 °C, K: 125 °C, L: 150 °C</p> <p>Package type UA:TO-92S,VK:TO-92S(4pin),VF:TO-92S(5pin),SO:SOT-23, SQ:QFN-3,ST:TSOT-23,SN:SOT-553,SF:SOT-89(5pin), SS:TSOT-26,SD:DFN-6</p> <p>Sorting α, β, Blank.....</p>
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Part No.	Temperature Suffix	Package Type
MH180KUA	K (-40°C to + 125°C)	UA (TO-92S)
MH180KSO	K (-40°C to + 125°C)	SO (SOT-23)
MH180EUA	E (-40°C to + 85°C)	UA (TO-92S)
MH180ESO	E (-40°C to + 85°C)	SO (SOT-23)

KUA spec is using in industrial and automotive application. Special Hot Testing is utilized.

Functional Diagram



Absolute Maximum Ratings At ($T_a=25\text{ }^\circ\text{C}$)

Characteristics		Values	Unit
Supply voltage, (V_{DD})		28	V
Output Voltage, (V_{out})		28	V
Reverse voltage, (V_{DD})		-28	V
Magnetic flux density		Unlimited	Gauss
Output current, (I_{out})		50	mA
Operating Temperature Range, (T_a)	“E” version	-40 to +85	$^\circ\text{C}$
	“K” version	-40 to +125	$^\circ\text{C}$
Storage temperature range, (T_s)		-65 to +150	$^\circ\text{C}$
Maximum Junction Temp, (T_j)		150	$^\circ\text{C}$
Thermal Resistance	(θ_{ja}) UA / SO	206 / 543	$^\circ\text{C}/\text{W}$
	(θ_{jc}) UA / SO	148 / 410	$^\circ\text{C}/\text{W}$
Package Power Dissipation, (P_D) UA / SO		606 / 230	mW

Note: Do not apply reverse voltage to V_{DD} and V_{OUT} Pin, It may be caused for Miss function or damaged device.

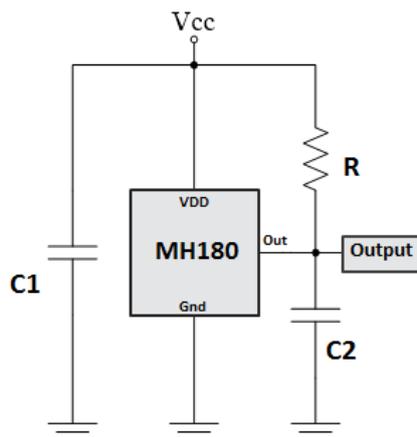
Electrical Specifications

DC Operating Parameters : $T_A=+25\text{ }^\circ\text{C}$, $V_{DD}=12\text{V}$

Parameters	Test Conditions	Min	Typ	Max	Units
Supply Voltage, (V_{DD})	Operating	2.5		24.0	V
Supply Current, (I_{DD})	B<BOP			5.0	mA
Output Saturation Voltage, (V_{sat})	$I_{out}=20\text{mA}$, B>BOP			400.0	mV
Output Leakage Current, (I_{off})	I _{OFF} B<BRP, $V_{OUT} = 12\text{V}$			10.0	μA
Output Rise Time, (T_R)	$R_L=1.1\text{K}\Omega$, $C_L=20\text{pF}$		0.04	0.45	μs
Output Fall Time, (T_F)	$R_L=820\Omega$; $C_L=20\text{pF}$		0.18	0.45	μs
Electro-Static Discharge	HBM	4			KV
Operate Point, (B_{OP})	UA(SO)		45		Gauss
Release Point, (B_{RP})	UA(SO)		-45		Gauss
Hysteresis, (B_{HYS})			90		Gauss

Typical application circuit

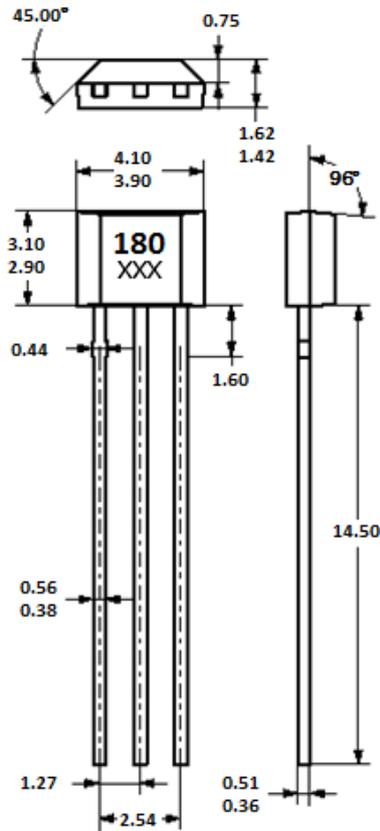
Sensor Location, Package Dimension and Marking



R : $1\text{K}\Omega$
 C1 : 10nF
 C2 : 1nF

MH180 Package

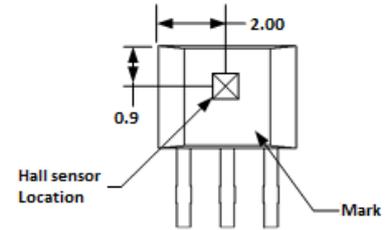
UA Package



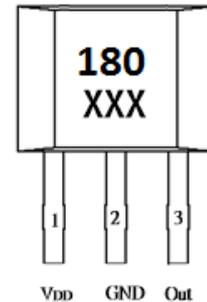
NOTES:

- 1).Controlling dimension: mm
 - 2).Leads must be free of flash and plating voids
 - 3).Do not bend leads within 1 mm of lead to package interface.
 - 4).PINOUT:
- | | |
|-------|-----------------|
| Pin 1 | V _{DD} |
| Pin 2 | GND |
| Pin 3 | Output |

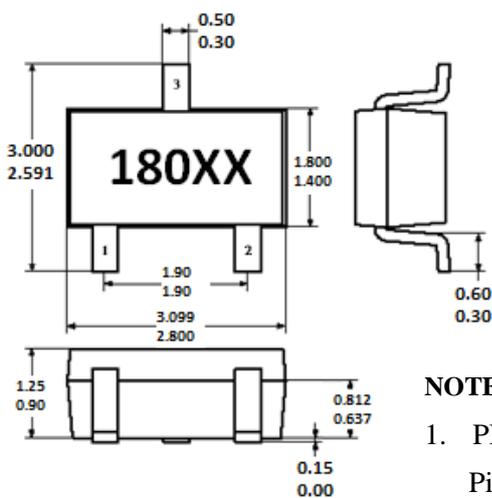
Hall Chip location



Output Pin Assignment
(Top view)



SO Package
(Top View)



NOTES:

1. PINOUT (See Top View at left :)
- | | |
|-------|-----------------|
| Pin 1 | V _{DD} |
| Pin 2 | Output |
| Pin 3 | GND |
2. Controlling dimension: mm
 3. Lead thickness after solder plating will be 0.254mm maximum

Hall Plate Chip Location
(Bottom view)

